

1-1932000-0 ✓ ACTIVE

DDR3 DIMM, DDR3 SO DIMM

TE Internal #: 1-1932000-0

DIMM Sockets, Double Data Rate (DDR) 3, Board-to-Board, 240

Position, Through Hole - Solder, Vertical Module Orientation, DDR3

DIMM

[View on TE.com >](#)



Connectors > Socket Connectors > Memory Sockets > DIMM Sockets > DDR3 DIMM Sockets



DRAM Type: **Double Data Rate (DDR) 3**

Connector System: **Board-to-Board**

Number of Positions: **240**

Termination Method to Printed Circuit Board: **Through Hole - Solder**

Module Orientation: **Vertical**

[All DDR3 DIMM Sockets \(13\)](#)

## Features

### Product Type Features

DRAM Type	Double Data Rate (DDR) 3
Connector System	Board-to-Board
Connector & Contact Terminates To	Printed Circuit Board

### Configuration Features

Number of Bays	2
Number of Keys	1
Number of Rows	2
Number of Positions	240
Module Orientation	Vertical

### Electrical Characteristics

DRAM Voltage	1.5 V
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### Body Features



PCB Retention Feature Material	Brass
Ejector Material Color	Natural
Ejector Material	High Temperature Nylon
Latch Color	Natural
Ejector Location	Both Ends
Latch Material	Thermoplastic
Retention Post Location	Center
Module Key Type	Offset Left
Ejector Type	Standard

### Contact Features

Memory Socket Type	Memory Card
Socket Style	DIMM
PCB Contact Termination Area Plating Material Thickness	3 $\mu\text{m}$ [118.1 $\mu\text{in}$ ]
Contact Mating Area Plating Material Thickness	.38 $\mu\text{m}$ [15 $\mu\text{in}$ ]
Contact Mating Area Plating Material	Gold
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Copper Alloy
Contact Current Rating (Max)	.75 A

### Termination Features

Insertion Style	Direct Insert
Termination Post & Tail Length	2.67 mm[.105 in]
Termination Method to Printed Circuit Board	Through Hole - Solder

### Mechanical Attachment

Mount Angle	Vertical
Mating Alignment Type	Center
Mating Alignment	With
PCB Mount Retention	With
PCB Mount Retention Type	Retention Clip/Post
Connector Mounting Type	Board Mount

### Housing Features

Housing Material	High Temperature Nylon
Housing Color	Black



Centerline (Pitch)	1 mm[.039 in]
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### Dimensions

Center Retention Hole Diameter	1.8 mm[.07 in]
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Profile Height from PCB	23.1 mm[.9 in]
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Row-to-Row Spacing	1.9 mm[.075 in]
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### Usage Conditions

Operating Temperature Range	-55 – 155 °C[-67 – 311 °F]
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### Operation/Application

Circuit Application	Signal
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### Industry Standards

UL Flammability Rating	UL 94V-0
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### Packaging Features

Packaging Quantity	50
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Packaging Method	Tray
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### Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
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EU ELV Directive 2000/53/EC	Compliant
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China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
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EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2022 (224) Does not contain REACH SVHC
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Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
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Solder Process Capability	Wave solder capable to 260°C
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#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits



as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

## Compatible Parts



## Also in the Series | DDR3 DIMM

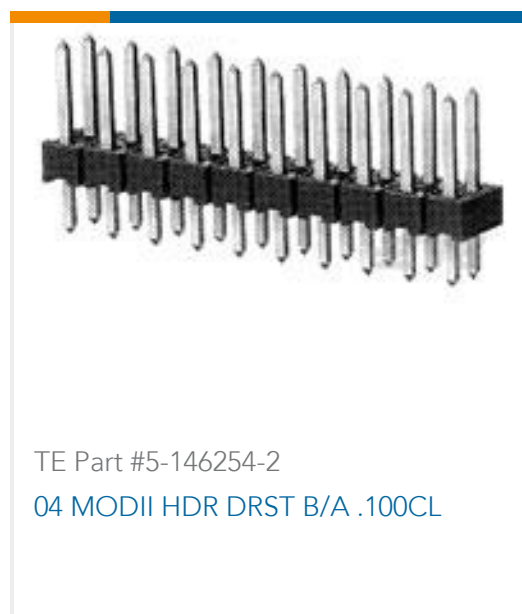


## Also in the Series | DDR3 SO DIMM



## Customers Also Bought





## Documents

### Product Drawings

[VERTICAL DDR3 DIMM, 240 POSITION](#)

English

### CAD Files

Customer View Model

[ENG\\_CVM\\_CVM\\_1-1932000-0\\_F.2d\\_dxf.zip](#)

English

[3D PDF](#)

3D

Customer View Model

[ENG\\_CVM\\_CVM\\_1-1932000-0\\_F.3d\\_igs.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_1-1932000-0\\_F.3d\\_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

### Datasheets & Catalog Pages

[6-1773457-3\\_DDR3\\_DIMM\\_SOCKETS](#)

### Product Specifications

[Product Specification](#)

English